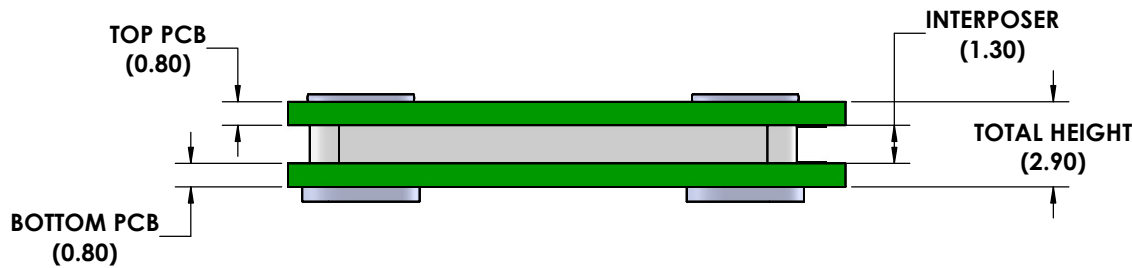
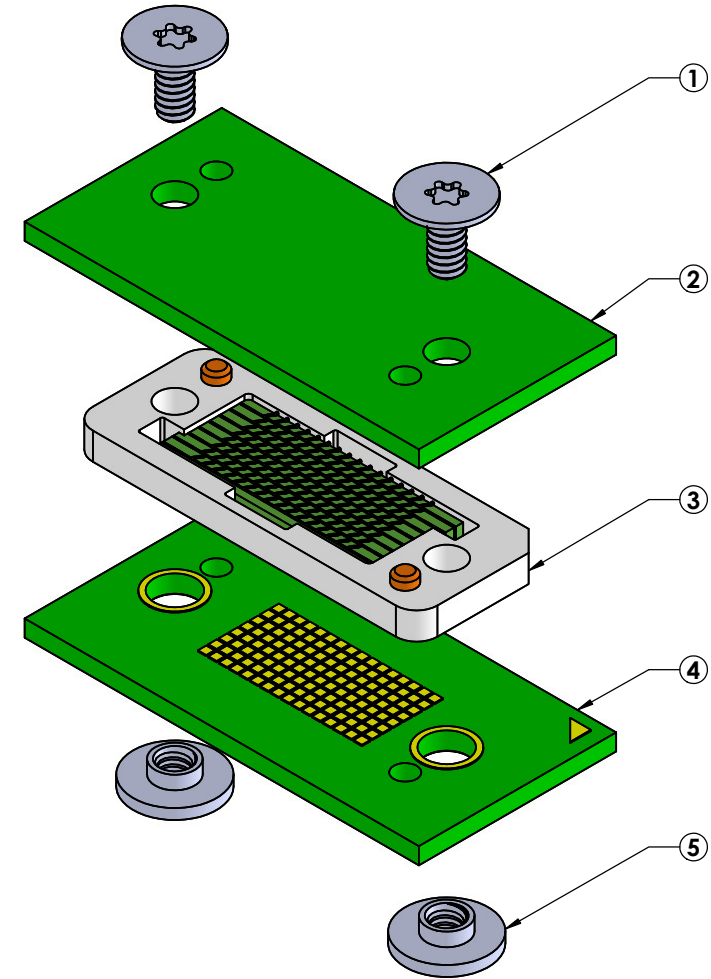
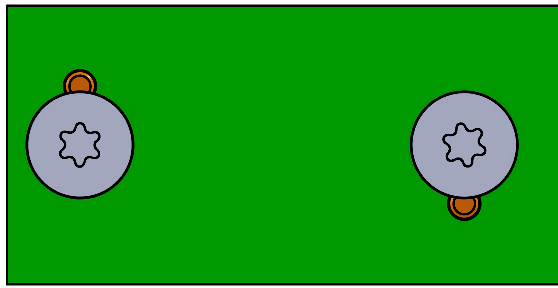


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PERMISSION OF NEOCONIX.

REVISION				
REV	ECN	DESCRIPTION	DATE	DESIGN BY
1	0000	INITIAL RELEASE	02/20/2024	TAN

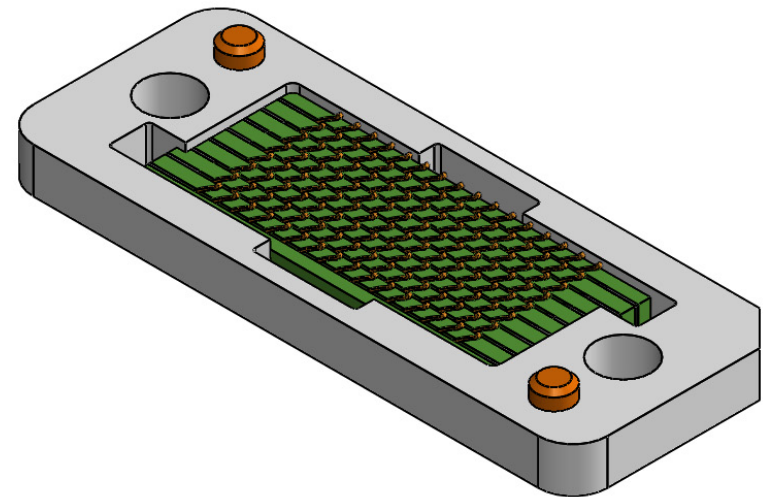
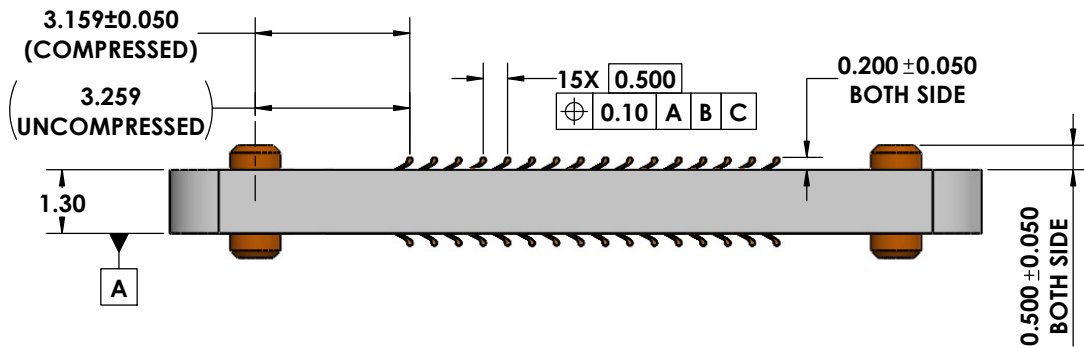
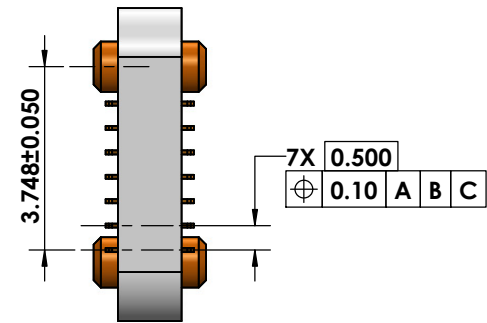
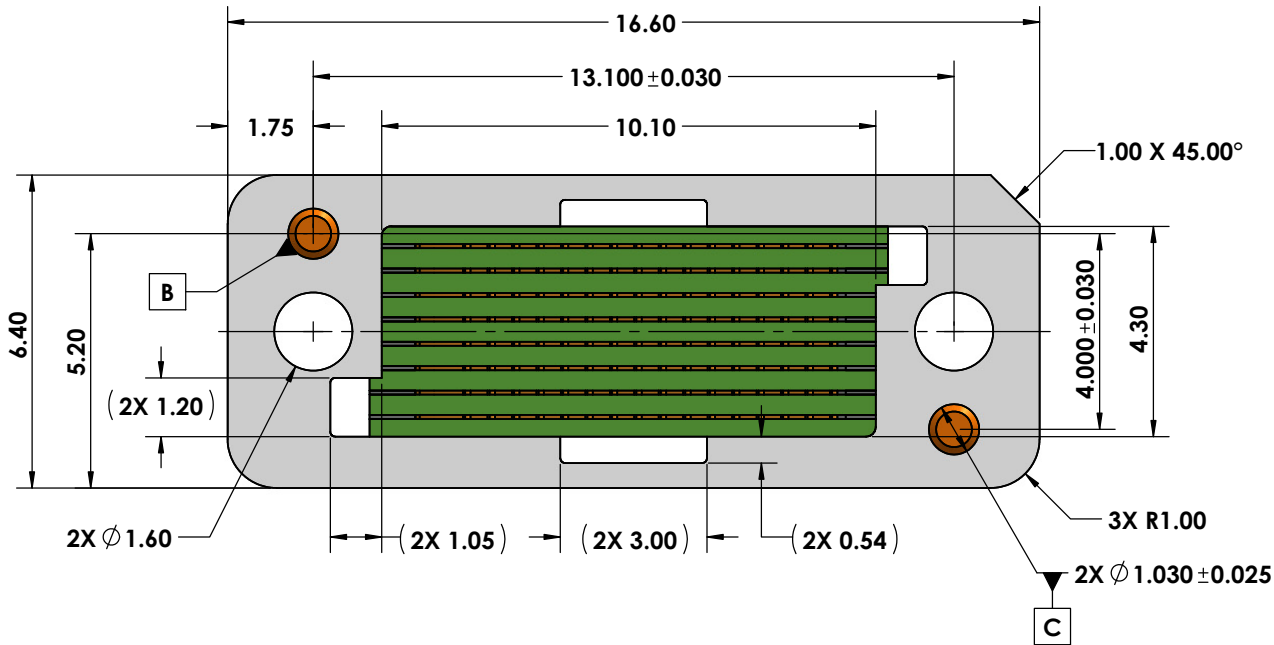


ITEM	DESCRIPTION	NEOCONIX P/N	QTY PER ASSY
1	M1.4 Waferhead Screw	Various *	2
2	TOP PCB	N/A – Customer Supplied	1
3	INTERPOSER	SPH2-XB128A	1
4	BOTTOM PCB	N/A – Customer Supplied	1
5	M1.4 NUT	B01-000581	2

* See **AS-000083** for various part number options based on assembly thickness stackup. All items ordered separately.

<p>4020 MOORPARK AVENUE #108 SAN JOSE, CA 95117 USA TEL: 408-530-9393 FAX: 408-530-9383</p>	DIMENSIONS ARE IN MM [INCH] .X ±0.13 .XX ±0.08 .XXX ±0.025 ANGLE: NO DEC±2 DEGREE .X± .XX±	MATERIAL: SEE NOTES FINISH:	TITLE: CBM ASSEMBLY 128 POS LGA-LGA	
	DRAWN BY: TAN NGUYEN 2/20/2024 CHECKED BY: ENGR APPR: MFG APPR: QA APPR:	SIZE: B+	DWG NUMBER: CBM-XB128A	REV: 1
	THIRD ANGLE	SCALE: 5:1	SHEET 1 OF 4	

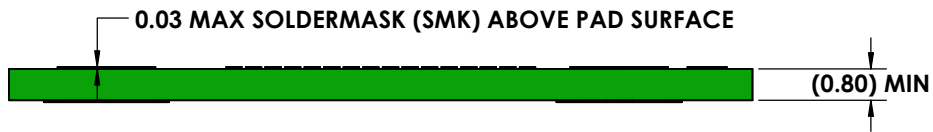
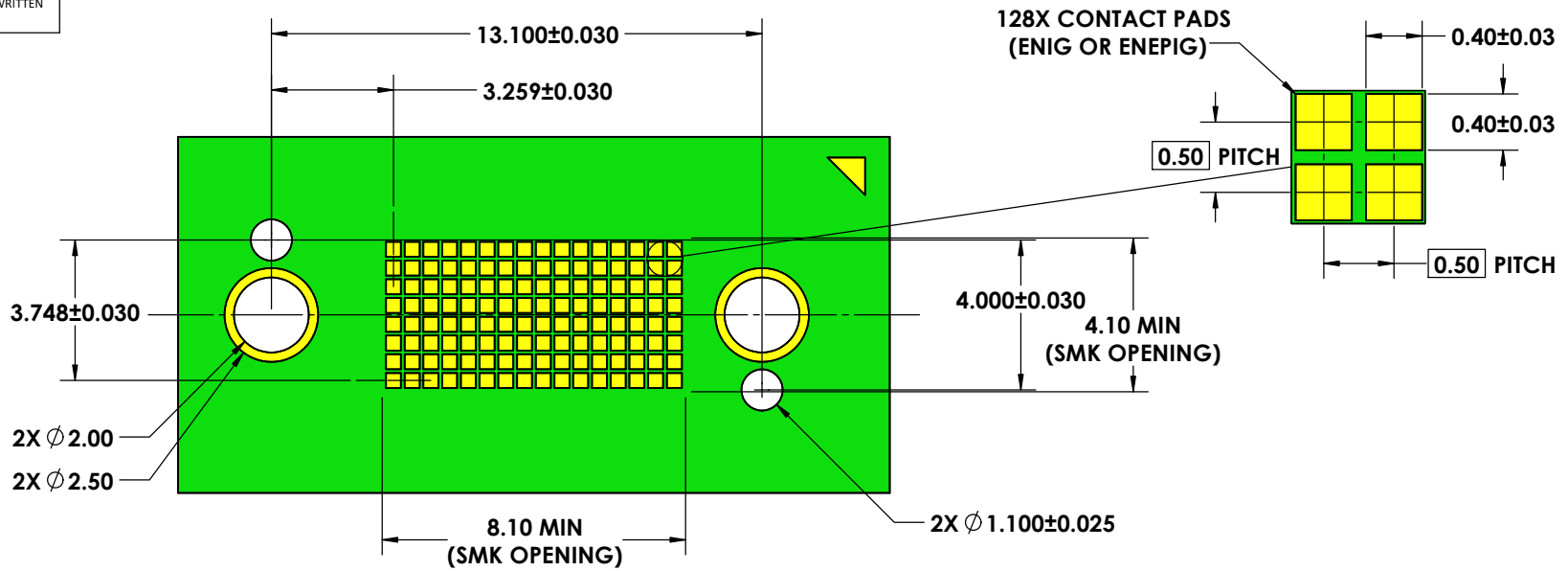
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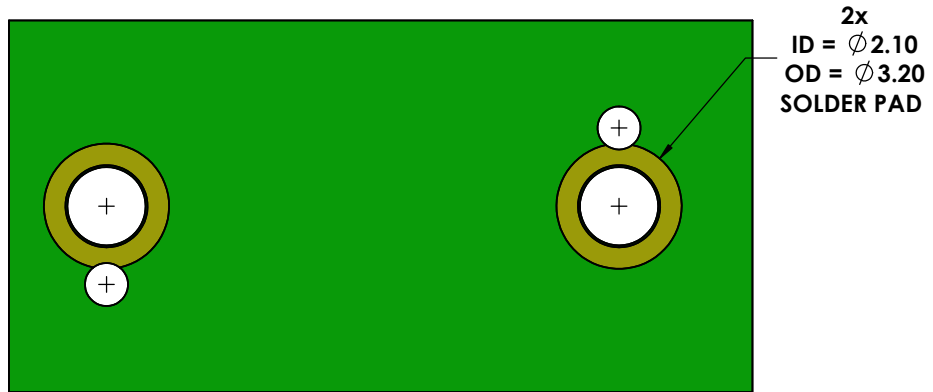
NOTES (UNLESS OTHERWISE SPECIFIED):

1. INTERPRET DRAWING PER ASME Y14.5M-1994.
2. HALOGEN-FREE PER IPC-4101B.
3. COMPLIANT WITH RoHS DIRECTIVE 2011/65/EU.
4. CENTER MARKS OF CONTACT POSITIONS ARE FOR COMPRESSED STATE.
5. FRAME MATERIAL : LCP.

<p>4020 MOORPARK AVENUE #108 SAN JOSE, CA 95117 USA TEL: 408-530-9393 FAX: 408-530-9383</p>	DIMENSIONS ARE IN MM [INCH]		MATERIAL: SEE NOTES		TITLE: CBM INTERPOSER 128 POS LGA-LGA	
	.X ±0.13	✓	FINISH:	DRAWN BY: TAN NGUYEN 2/20/2024		SIZE: B+
	.XX ±0.08		CHECKED BY:	ENGR APPR:		
	.XXX ±0.025		ANGLE: NO DEC ± 2 DEGREE X ± XX ±	MFG APPR:		DWG NUMBER: CBM-XB128A
		THIRD ANGLE	QA APPR:		REV: 1	
				SCALE: 5:1		SHEET 2 OF 4



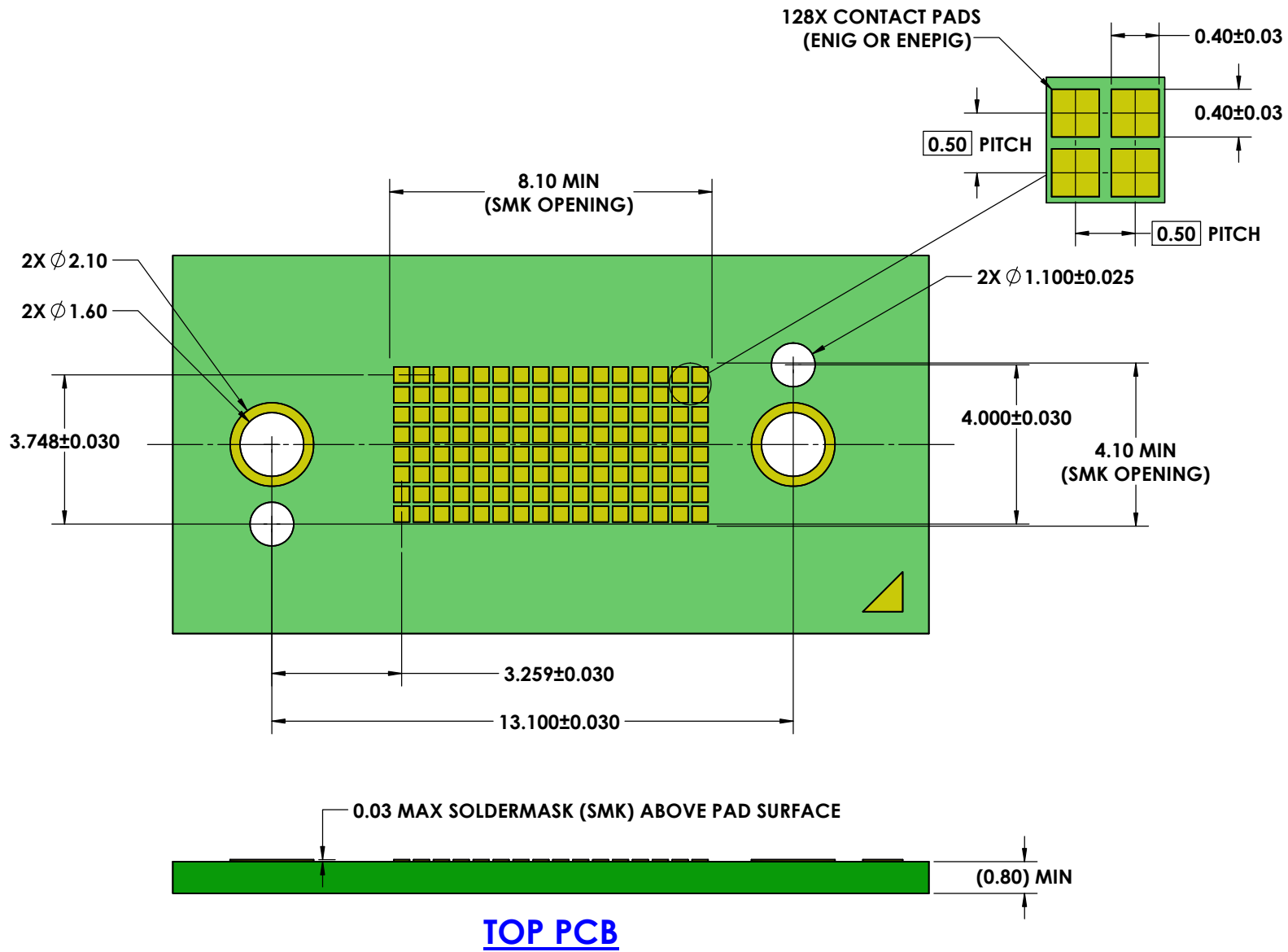
BOTTOM PCB



NOTES (UNLESS OTHERWISE SPECIFIED):

1. IF THE VIA NEEDS TO BE LOCATED WITHIN THE 0.40 X 0.40 PAD, IT MUST BE FILLED, PLATED, AND PLANARIZED WITH 25µm MAX DIMPLE.
2. SOLDERMASK APPLICATION IN THE ARRAY AREA IS OPTIONAL. IF APPLIED, IT SHALL NOT PROTRUDE MORE THAN 0.03mm ABOVE THE SURFACE OF THE MATING PADS.

<p>4020 MOORPARK AVENUE #108 SAN JOSE, CA 95117 USA TEL: 408-530-9393 FAX: 408-530-9383</p>	DIMENSIONS ARE IN MM [INCH] .X ±0.13 .XX ±0.08 .XXX ±0.025 ANGLE: NO DEC±2 DEGREE .X± .XX±	MATERIAL: SEE NOTES FINISH: <input checked="" type="checkbox"/>	TITLE: RECOMMENDED PCB LAYOUT CBM-XB128A	
	DRAWN BY: TAN NGUYEN 2/20/2024 CHECKED BY: ENGR APPR: MFG APPR: QA APPR:	SIZE: B+	DWG NUMBER: CBM-XB128A-PCB	REV 1
	THIRD ANGLE	SCALE: 5:1	SHEET 3 OF 4	



NOTES (UNLESS OTHERWISE SPECIFIED):

1. IF THE VIA NEEDS TO BE LOCATED WITHIN THE 0.40 X 0.40 PAD, IT MUST BE FILLED, PLATED, AND PLANARIZED WITH 25um MAX DIMPLE.
2. SOLDERMASK APPLICATION IN THE ARRRY AREA IS OPTIONAL. IF APPLIED, IT SHALL NOT PROTRUDE MORE THAN 0.03mm ABOVE THE SURFACE OF THE MATING PADS.

<p>necconix 4020 MOORPARK AVENUE #108 SAN JOSE, CA 95117 USA TEL: 408-530-9393 FAX: 408-530-9383</p>	DIMENSIONS ARE IN MM [INCH] .X ±0.13 .XX ±0.08 .XXX ±0.025 ANGLE: NO DEC±2 DEGREE .X± .XX±		MATERIAL: SEE NOTES FINISH:		TITLE: RECOMMENDED PCB LAYOUT CBM-XB128A	
	DRAWN BY: TAN NGUYEN 2/20/2024		CHECKED BY:		SIZE: B+	
	ENGR APPR:		MFG APPR:		DWG NUMBER: CBM-XB128A-PCB	
	QA APPR:		THIRD ANGLE		REV: 1	
				SCALE: 5:1		
				SHEET 4 OF 4		